## 503726166 03/08/2016

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
YI-JING LEE	10/27/2014
KUN-MU LI	10/28/2014
CHII-HORNG LI	10/28/2014
TZE-LIANG LEE	10/28/2014

### **RECEIVING PARTY DATA**

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	
Street Address:	NO. 8, LI-HSIN ROAD 6,	
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK	
City:	HSIN-CHU	
State/Country:	TAIWAN	
Postal Code:	300-77	

## **PROPERTY NUMBERS Total: 1**

Property Type	Number	
Application Number:	15063694	

## **CORRESPONDENCE DATA**

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ATTORNEY DOCKET NUMBER: 24061.3006US02

NAME OF SUBMITTER: LADONNA JOHNSON

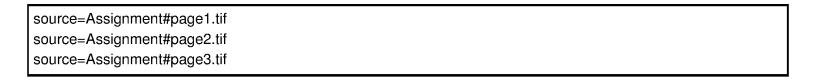
SIGNATURE: /LaDonna Johnson/

DATE SIGNED: 03/08/2016

Total Attachments: 3

PATENT REEL: 037918 FRAME: 0995

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PATENT REEL: 037918 FRAME: 0996 yjleef 2014/10/27 10:48:08

TSMC No. 2014-0964 / Attorney Docket No. 24061.3006 Customer No.: 000042717

#### ASSIGNMENT

WHEREAS, we,

(1)	Yi-Jing Lee	of	2F., No. 87, Ln. 19, Guanxin Road East District Hsinchu City 300, Taiwan R.O.C.
(2)	Kun-Mu Li	of	No. 111, Furong Street, Zhudong Township Hsinchu County 310, Taiwan R.O.C.
(3)	Chii-Horng Li	of	No. 137, Wencai Street, Zhubei City Hsinchu County 302, Taiwan R.O.C.
(4)	Tze-Liang Lee	of	4F, No. 74, Lane 250 Wu-ling Rd. Hsinchu, Taiwan, R.O.C.

have invented certain improvements in

### STRUCTURE AND METHOD FOR SEMICONDUCTOR DEVICE

for which we have executed an application for Letters Patent of the United States of America,

\_\_\_\_\_\_ of even date filed herewith; and
\_\_\_\_\_\_ and assigned application number \_\_\_\_\_\_; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

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R-3006 - Assignment (10-23)

TSMC No. 2014-0964 / Attorney Docket No. 24061.3006 Customer No.: 000042717

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name:	Yi-Jing Lee	
Residence Address:	2F., No. 87, Ln. 19, Guanxin Ro Hsinchu City 300, Taiwan R.O.	
Dated: <u> </u>	}	Ys Jong Lel Inventor Signature
Inventor Name:	Kun-Mu Li	
Residence Address:	No. 111, Furong Street, Zhudong Township Hsinchu County 310, Taiwan R.O.C.	
Dated:	. **	Inventor Signature
Inventor Name:	Chii-Horng Li	
Residence Address:	No. 137, Wencai Street, Zhubei Hsinchu County 302, Taiwan, R	
Dated: 19/28/2010	<b>i</b> -	Chiù-Horng Li
		Inventor Signature

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TSMC No. 2014-0964 / Attorney Docket No. 24061.3006

Customer No.: 000042717

Inventor Name:

Tze-Liang Lee

Residence Address:

4F, No. 74, Lane 250 Wu-ling Rd., Hsinchu, Taiwan, R.O.C.

Dated: 10/28, 2014

Inventor Signature

R-3006 - Assignment (10-23)

**RECORDED: 03/08/2016** 

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PATENT REEL: 037918 FRAME: 0999